Abstract

A cutting device of a silicon rod cutting system, and the silicon rod cutting system. The cutting device includes: a support frame, installed on a machine base of the silicon rod cutting system; two cutting machine head mechanisms, wherein each cutting machine head mechanism is provided with a diamond wire, a cutting segment of the diamond wire is used for cutting a silicon rod from top to bottom while moving; and a feeding mechanism, wherein the support frame is connected with the two cutting machine head mechanisms by means of the feeding mechanism, and the two cutting segments are disposed opposite to each other; and the feeding mechanism is used for driving the two cutting machine head mechanisms to move towards and away from each other, so as to adjust the distance between the two cutting segments.